INTERCONNECTED-MULTI-ELEMENT-LATTICE POLISHING PAD

Abstract

The polishing pad (104) is useful for polishing at least one of magnetic, optical and semiconductor substrates (112) in the presence of a polishing medium (120). The polishing pad (104) includes a plurality of polishing elements (402, 502, 602, 702). The polishing elements (402, 502, 602, 702) are aligned in a vertical direction and having a first and a second end. A plurality of junctions (404, 510, 610, 710) connects the first and second ends of the polishing elements (402, 502, 602, 702) with at least three polishing elements at each of the plurality of junctions (404, 510, 610, 710) for forming a tier. Each tier representing a thickness in the vertical direction between the first and second ends of the polishing elements (402, 502, 602, 702). And an interconnected lattice structure (400, 600) forms from connecting sequential tiers of the plurality of junctions (404, 504) that connect the polishing elements (402, 502, 602, 702).